

Notification Number:	20220809000.0	Notification Date:	August 09, 2022
Title:	Datasheet for TMS320F2833x, TMS320F2823x		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.

[TMS320F28335](#), [TMS320F28335-Q1](#), [TMS320F28334](#), [TMS320F28333](#)
[TMS320F28332](#), [TMS320F28235](#), [TMS320F28235-Q1](#)
[TMS320F28234](#), [TMS320F28234-Q1](#), [TMS320F28232](#), [TMS320F28232-Q1](#)
SPRS439Q – JUNE 2007 – REVISED AUGUST 2022



Changes from February 2, 2021 to August 8, 2022 (from Revision P (February 2021) to Revision Q (August 2022))

Page

• Global: Changed document title from <i>TMS320F2833x, TMS320F2823x Digital Signal Controllers (DSCs)</i> to <i>TMS320F2833x, TMS320F2823x Real-Time Microcontrollers</i>	1
• Global: Changed "digital signal controller" to "real-time microcontroller". Changed "DSC" to "MCU".	1
• Global: Due to an equipment End-of_Life notice from our substrate supplier, we are phasing out certain MicroStar BGA™ packaging devices. These devices have now been converted to a New Fine Pitch Ball Grid Array (nFBGA) package. For more information, see the Package Redesign Details section.....	1
• Global: Added 179-ball ZAY New Fine Pitch Ball Grid Array (nFBGA).....	1
• Global: Changed title of errata from <i>TMS320F2833x, TMS320F2823x DSCs Silicon Errata</i> to <i>TMS320F2833x, TMS320F2823x Real-Time MCUs Silicon Errata</i>	1
• Global: Replaced references to peripheral reference guides with references to the TMS320x2833x, TMS320x2823x Real-Time Microcontrollers Technical Reference Manual	1
• Global: Replaced "emulator" with "JTAG debug probe".....	1
• Section 1 (Features): Changed "Advanced emulation features" to "Advanced debug features".....	1
• Section 1: Added "179-ball New Fine Pitch Ball Grid Array (nFBGA) [ZAY]" to "Package options".....	1
• Section 1: Added "ZAY" to Temperature option "A".....	1
• Section 2 (Applications): Updated section.....	2
• Section 3 (Description): Updated section. Changed Device Information table to Package Information table. Added ZAY nFBGA to Package Information table.....	2
• Table 5-1 (F2833x Device Comparison): Appended "(UART-compatible)" to "Serial Communications Interface (SCI)".....	8
• Table 5-1: Added "179-Ball ZAY" to Packaging section. Added ZAY to "A" Temperature option.....	8
• Table 5-2 (F2823x Device Comparison): Appended "(UART-compatible)" to "Serial Communications Interface (SCI)".....	8
• Table 5-2: Added "179-Ball ZAY" to Packaging section. Added ZAY to "A" Temperature option.....	8
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• Section 6.1 (Pin Diagrams): Added 179-ball ZAY new fine pitch ball grid array (nFBGA).....	12
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• Section 7.9.2 (Power Sequencing): Updated "No requirements are placed on the power-up and power-down sequences ..." paragraph.....	48
• Section 7.9.5: Changed section title from "Emulator Connection Without Signal Buffering for the DSP" to "JTAG Debug Probe Connection Without Signal Buffering for the MCU".....	79

- [Figure 7-27](#): Changed figure title from "Emulator Connection Without Signal Buffering for the DSP" to "JTAG Debug Probe Connection Without Signal Buffering for the MCU"..... 79
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- [Section 10.3](#) (Tools and Software): Updated section. Updated Design Kits and Evaluation Modules section. Updated Models section. Added Training section..... 184
- [Section 10.4](#) (Documentation Support): Added *nFBGA Packaging Application Report*..... 186
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- [Section 10.4](#): Updated **Peripheral Guides** section. Removed most peripheral reference guides as they are now replaced by the *TMS320x2833x, TMS320x2823x Real-Time Microcontrollers Technical Reference Manual*..... 186
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The datasheet number will be changing.

Device Family	Change From:	Change To:
TMS320F2833x, TMS320F2823x	SPRS439P	SPRS439Q

These changes may be reviewed at the datasheet links provided.

<https://www.ti.com/product/TMS320F28335>

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Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:

None.

Product Affected:

SA320F28335ZJZQ	SP320F28335ZJZQR	TMS320F28232PTPQ	TMS320F28234PTPQ
TMS320F28234ZJZQ	TMS320F28235PTPQ	TMS320F28235ZJZQ	TMS320F28235ZJZQR
TMS320F28335PTPQ	TMS320F28335ZJZQ	TMS320F28335ZJZQCR	TMS320F28335ZJZQR

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